

ABSTRACT OF THE DISCLOSURE

The present invention discloses an image sensing semiconductor package and manufacture method thereof utilizing the plastic leaded chip carrier (PLCC)

5 manufacture process to produce image sensing chips with a cheaper plastic carrier, and it also seals dry high-pressure gas inside the image sensing chip in the manufacture process. Therefore, when the image sensing chip is used in a device, it can prevent moisture in
10 the air from entering into the interior of the image sensing component due to pressure difference that will shorten the lifespan of the image sensing chip. The invention also provides a component rinsing procedure for the image sensing semiconductor package manufacture process, so that no environmental factor of the manufacture process such as humidity and dust particles will affect the sensitivity of the chip or the normal display of the screen, and hence lower the defective rate of the product.